2018 IEEE/ACM International Conference on Technical Debt (TechDebt 2018)

Gothenburg, Sweden
27 May – 3 June 2018

*** This is a print representation of what appears in the IEEE Digital Library. Some format issues inherent in the e-media version may also appear in this print version.

Additional Copies of This Publication Are Available From:

2018 ACM/IEEE International Conference on Technical Debt
TechDebt 2018

Table of Contents

TechDebt 2018 - Incurring Debt

    Reem Alfayez (University of Southern California), Pooyan Behnamghader (University of Southern California), Kamonphop Srisopha (University of Southern California), and Barry Boehm (University of Southern California)

    Roberto Verdecchia (Gran Sasso Science Institute), Ivano Malavolta (Vrije Universiteit Amsterdam), and Patricia Lago (Vrije Universiteit Amsterdam)

TechDebt 2018 - Assessing Debt

    Luigi Lavazza (Università degli Studi dell'Insubria), Sandro Morasca (Università degli Studi dell'Insubria), and Davide Tosi (Università degli Studi dell'Insubria)

    Mashel Albarak (University of Birmingham; King Saud University) and Rami Bahsoon (University of Birmingham)

    Allan Mori (UFMG), Gustavo Vale (University of Passau), Markos Viggiato (UFMG), Johnatan Oliveira (PUC-Minas), Eduardo Figueiredo (UFMG), Elder Cirilo (UFSJ), Pooyan Jamshidi (CMU), and Christian Kastner (CMU)

TechDebt 2018 - Tools Track

TechDebt 2018 - Managing the Debt I (Short Papers)

TechDebt 2018 - Managing the Debt II

TechDebt 2018 - Practice in Industry

TechDebt 2018 - Future Research (Short Papers)